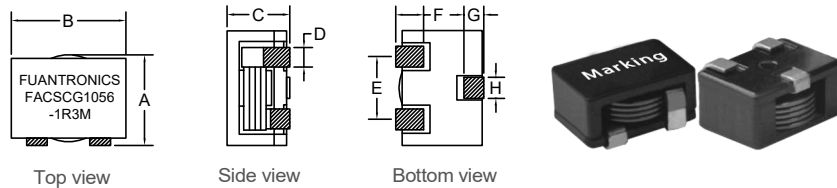


P/N: FACSCG1056-1R3M



Outline Dimensions(Unit:mm)

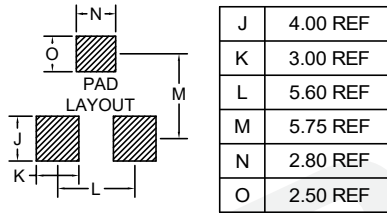


A	B	C	D	E	F	G	H
Max	Max	Max	±0.20	REF	±0.50	REF	REF
9.00	10.5	5.60	1.80	5.60	2.60	1.80	1.80

Electronical Schematic



Suggested Pad layout



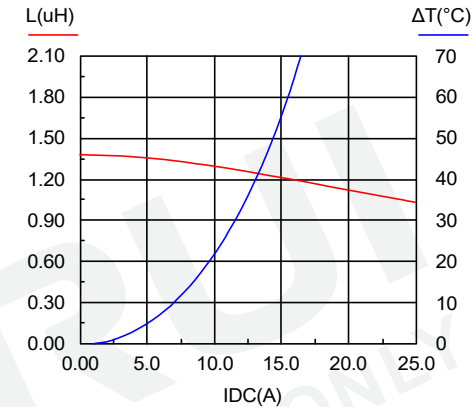
- ***Magnetic shielded structure: excellent resistance to electro magnetic interferenc(EMI).
- ***Assemblage design, sturdy structure.
- ***Small volume, high current, low magnetic loss, low ESR, small parasitic capacitance.
- ***Temperature rise current and saturation current is less influenced by environment.

Electrical Characteristics(@25°C)

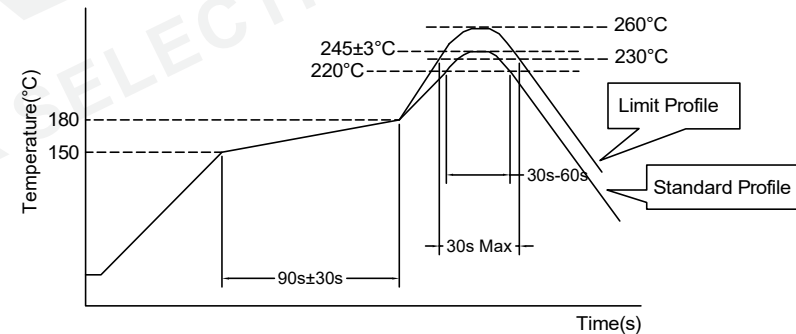
Inductance 100KHz,0.1V	DC Resistor	Saturated current 19A	Temperature rise current 13A
1.30uH±20%	2.80mΩ Max	L(19A)=80%*L0A Typ	T≤40°C Typ

- ***Saturation current: the actual value of DC current when the inductance decrease 20% of its initial value.
- ***Temperature rise current: the actual value of DC current when the temperature rise is ΔT40°C(Ta=25°C).
- ***Operating Temperature: -40°C~+125°C.
(Temperature rise included)
- ***Storage Temperature: -40°C~+125°C.
- ***Storage Humidity:RH10%~70%.

Saturation current VS temperature rise current curve:



Recommended Soldering Temperature Graph.



	Standard Profile	Standard Profile
Pre-heating	150~180°C,90s±30s	
Heating	above 220°C,30s-60s	above 240°C,30s Max
Peak temperature	245°C±3°C	260°C,10s
Cycle of reflow	2 times	2 times